

Features

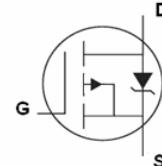
- P-Channel
- Low On-Resistance
- Very low on-resistance RDS(on) @ $V_{GS}=-4.5\text{ V}$
- Fast Switching
- High conversion efficiency
- Pb-free lead plating; RoHS compliant

V_{DS}	-30	V
$R_{DS(on),TYP}$ @ $V_{GS}=-10\text{ V}$	45	$\text{m}\Omega$
$R_{DS(on),TYP}$ @ $V_{GS}=-4.5\text{ V}$	55	$\text{m}\Omega$
I_D	-4.7	A

SOT23



Part ID	Package Type	Marking	Tape and reel information
VSC040P03MS	SOT23	4P03	3000pcs/reel


 Maximum ratings, at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
Common Ratings (Tc=25°C Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	± 12	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-30	V	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ\text{C}$	
I_S	Diode Continuous Forward Current	$T_c=25\text{ }^\circ\text{C}$	-4.7	A
Mounted on Large Heat Sink				
I_D	Continuous Drain current @ $V_{GS}=-10\text{ V}$	$T_c=25\text{ }^\circ\text{C}$	-4.7	A
		$T_c=100\text{ }^\circ\text{C}$	-3	A
I_{DM}	Pulse Drain Current Tested ①	$T_c=25\text{ }^\circ\text{C}$	-18	A
P_D	Maximum Power Dissipation	$T_c=25\text{ }^\circ\text{C}$	1.2	W
R_{JJC}	Thermal Resistance-Junction to Case	100	$^\circ\text{C}/\text{W}$	
R_{JA}	Thermal Resistance Junction-Ambient	80	$^\circ\text{C}/\text{W}$	

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_D=-250\mu\text{A}$	-30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=-24\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=-24\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$, $V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=-250\mu\text{A}$	-0.5	-1.0	-1.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=-10\text{V}$, $I_D=-3\text{A}$	--	45	55	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=-4.5\text{V}$, $I_D=-2\text{A}$	--	55	65	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=-3.3\text{V}$, $I_D=-1\text{A}$	--	65	85	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	--	550	--	pF
C_{oss}	Output Capacitance		--	110	--	pF
C_{rss}	Reverse Transfer Capacitance		--	70	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=-15\text{V}$, $I_D=-2\text{A}$, $V_{\text{GS}}=-4.5\text{V}$	--	7.2	--	nC
Q_{gs}	Gate-Source Charge		--	1.8	--	nC
Q_{gd}	Gate-Drain Charge		--	2.2	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}$, $I_D=-1\text{A}$, $R_G=6.8\Omega$, $V_{\text{GS}}=-10\text{V}$	--	9	--	nS
t_r	Turn-on Rise Time		--	7	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	22	--	nS
t_f	Turn-Off Fall Time		--	9	--	nS
Source- Drain Diode Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
I_{SD}	Source-drain current(Body Diode)	$T_c=25^\circ\text{C}$	--	--	-4.7	A
V_{SD}	Forward on voltage	$I_{\text{SD}}=-3\text{A}$, $V_{\text{GS}}=0\text{V}$	--	-0.85	-1.3	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}$, $I_{\text{sd}}=-2\text{A}$, $V_{\text{GS}}=0\text{V}$ $di/dt=-100\text{A}/\mu\text{s}$	--	13	--	nS
Q_{rr}	Reverse Recovery Charge		--	6.5	--	nC

NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

② Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

Typical Characteristics

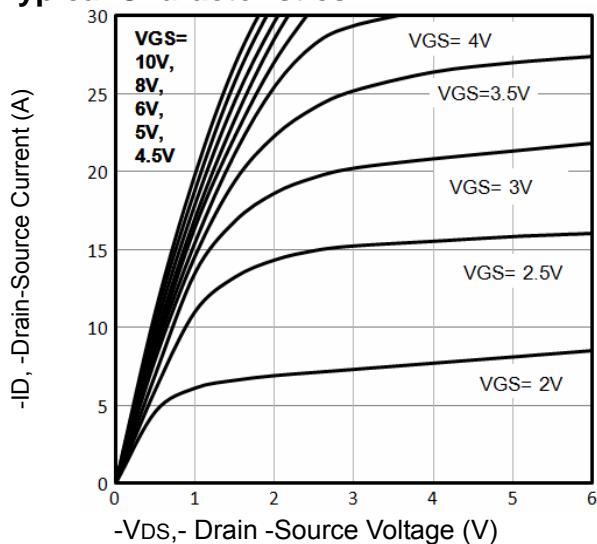


Fig1. Typical Output Characteristics

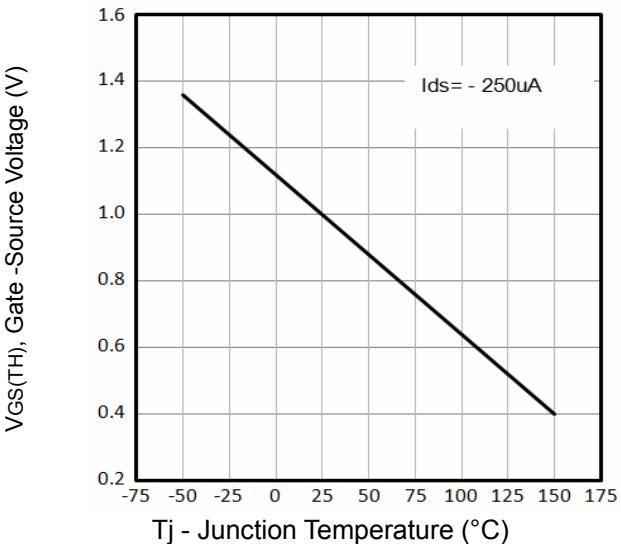


Fig2. Threshold Voltage Vs. Temperature

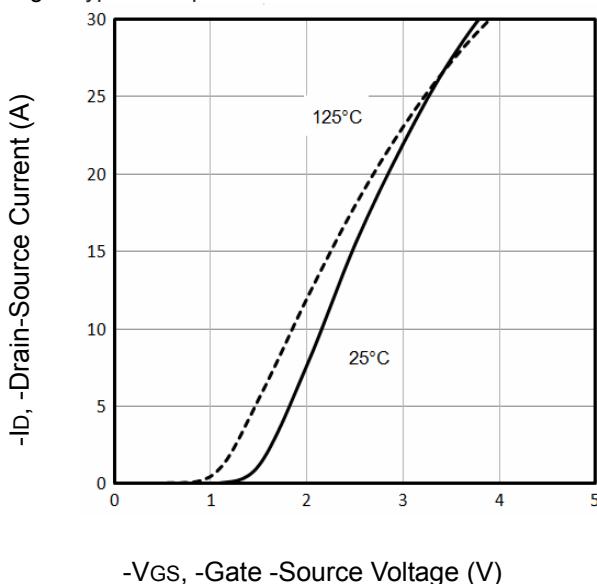


Fig3. Typical Transfer Characteristics

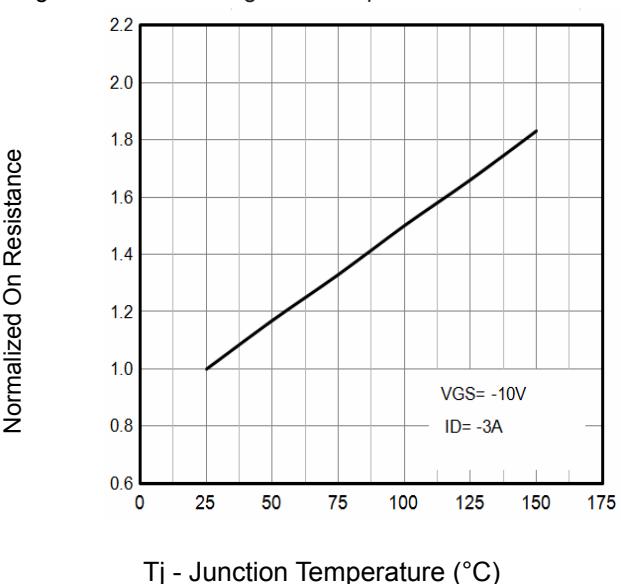


Fig4. Normalized On-Resistance Vs. Temperature

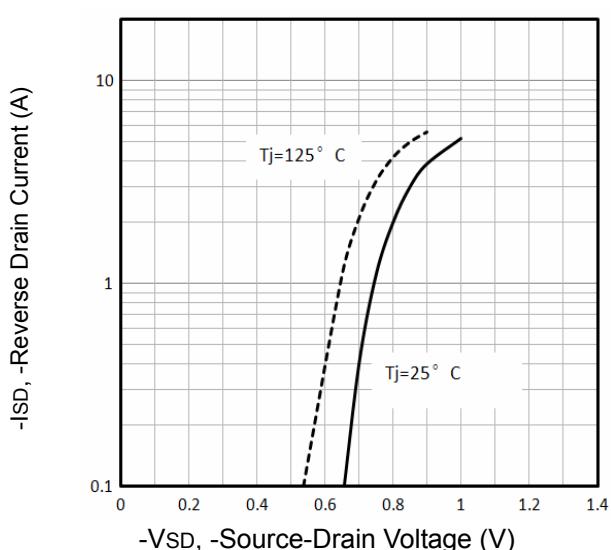


Fig5. Typical Source-Drain Diode Forward Voltage

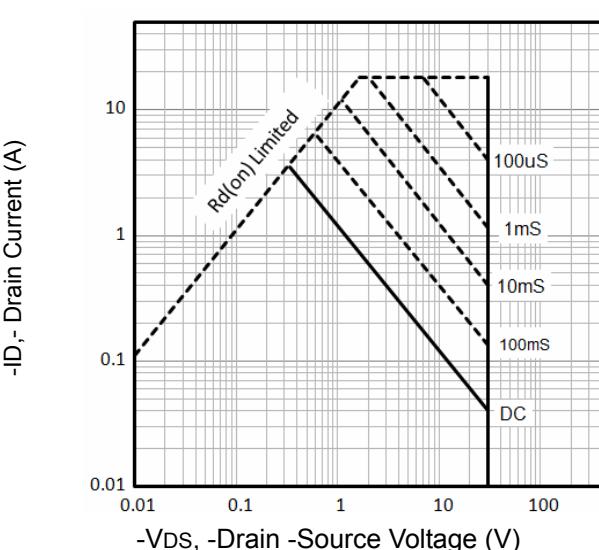


Fig6. Maximum Safe Operating Area

Typical Characteristics

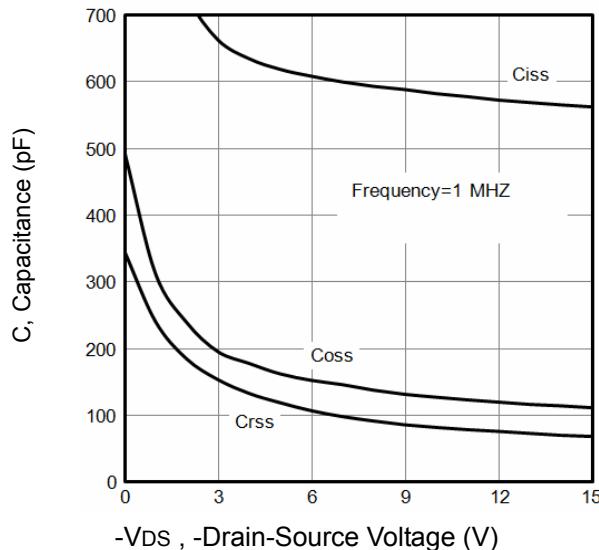


Fig7. Typical Capacitance Vs.Drain-Source Voltage

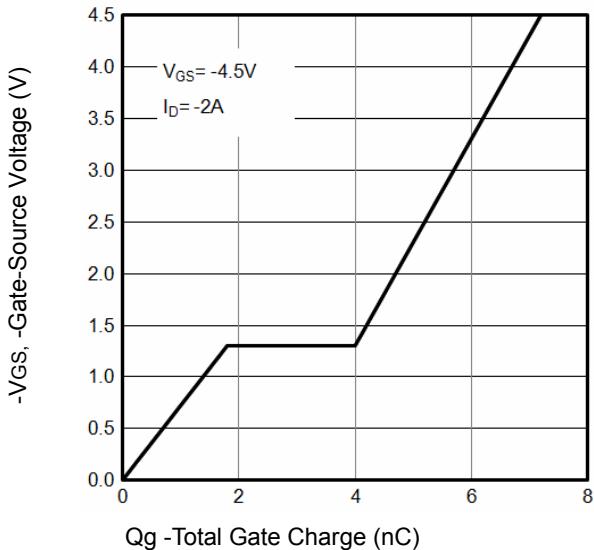


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

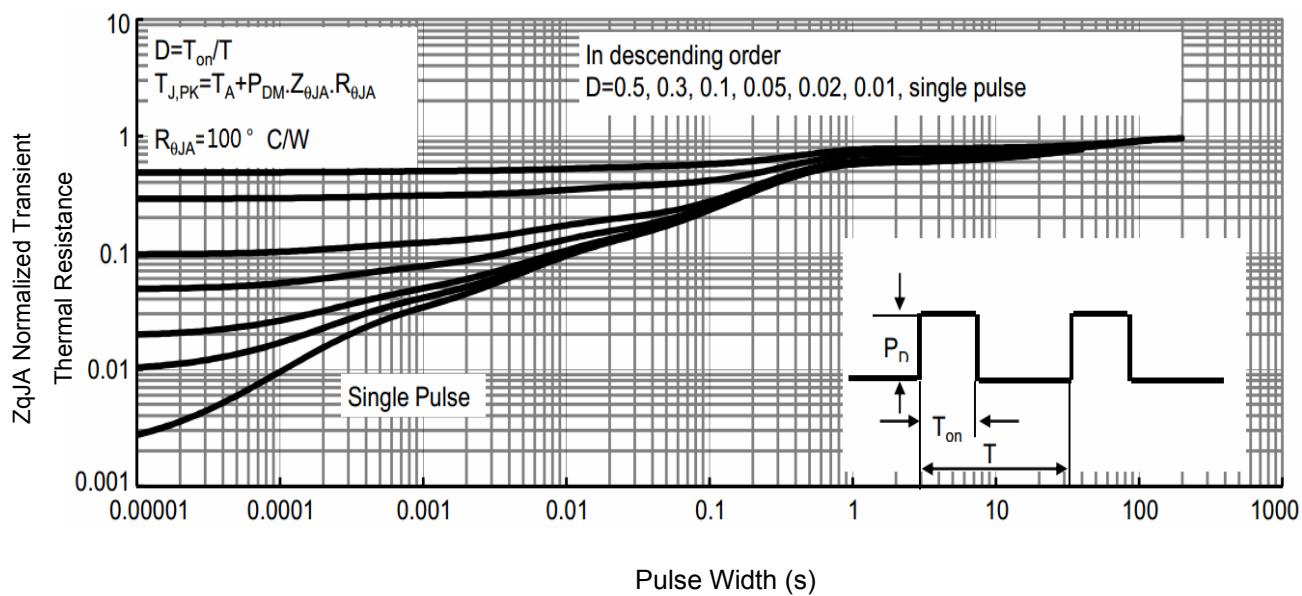


Figure 9: Normalized Maximum Transient Thermal

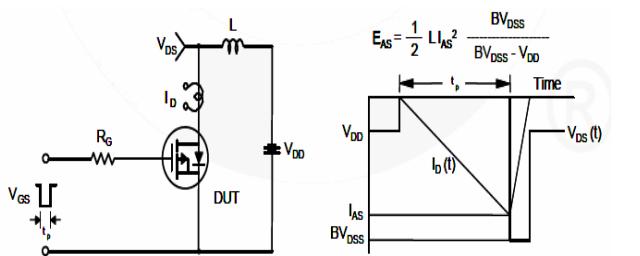


Fig10. Unclamped Inductive Test Circuit and Waveforms

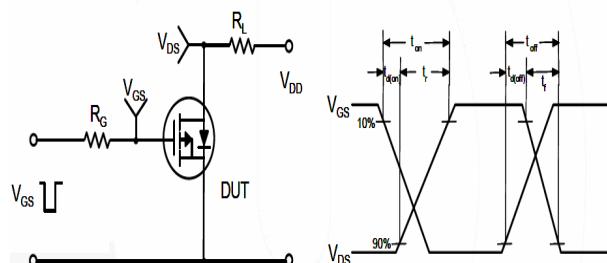
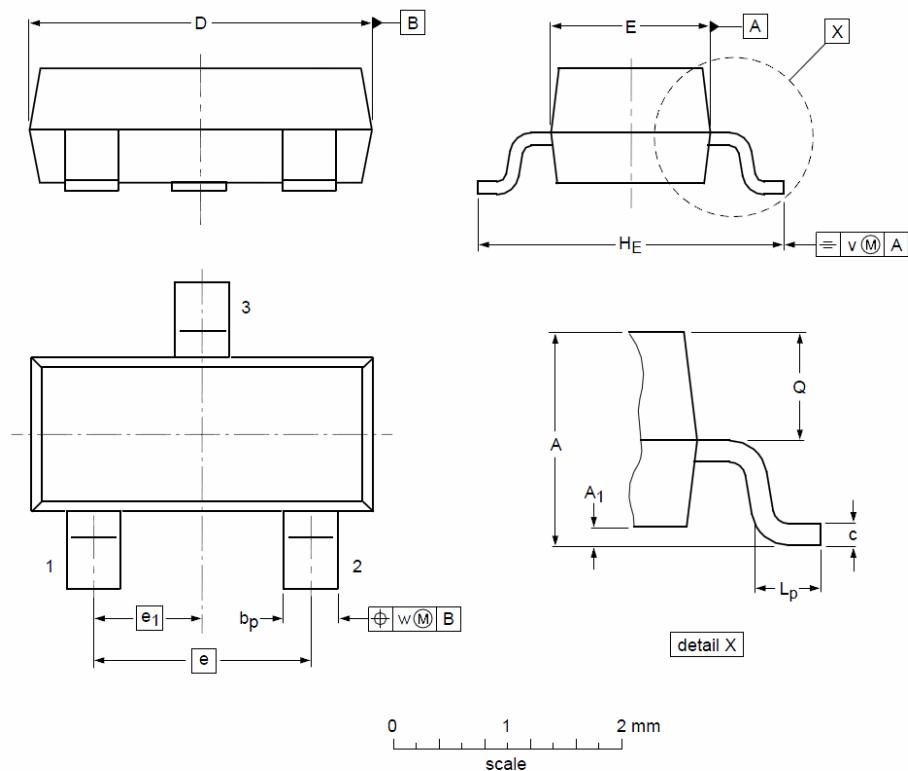


Fig11. Switching Time Test Circuit and waveforms

SOT23 Package Outline Data



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.03	1.10	A₁	0.01	0.05	0.10
b_p	0.38	0.42	0.48	c	0.09	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e₁	--	0.95	--
H_E	2.10	2.40	2.50	L_p	0.15	0.23	0.45
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				

Customer Service

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